

	Hit s	Search Text	DBs
29	2	S27 and S28	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
30	9	((substrate or wafer) same (ITO or (transparent near4 conductive near6 layer)) same (resist or photoresist) same (methacrylate or acrylate or polycarbonate or polyimide) same (lithography or expos\$4 or irradiat\$4 or illuminat\$4) same develop\$4 same (etch\$4 near28 (dry or RIE)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
31	18	((substrate or wafer) same (ITO or (transparent near4 conductive near6 layer) or (indium near4 tin near4 oxide)) same (resist or photoresist) same (methacrylate or acrylate or polycarbonate or polyimide) same (lithography or expos\$4 or irradiat\$4 or illuminat\$4)) and (develop\$4 same (etch\$4 near28 (dry or RIE)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
32	288	((substrate or wafer) same (ITO or (transparent near4 conductive near6 layer) or (indium near4 tin near4 oxide)) same (resist or photoresist) same (lithography or expos\$4 or irradiat\$4 or illuminat\$4)) and (develop\$4 same (etch\$4 near28 (dry or RIE)))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
33	185 58	((resist or photoresist) near26 (acrylate or methacrylate or polycarbonate or polyimide))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB

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<b>34</b>	34	S32 and S33	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB